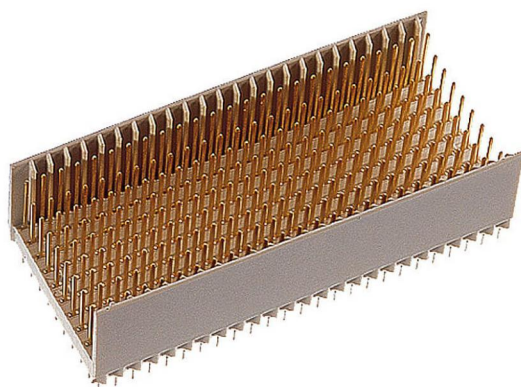


hm2.0 Male, type E, Part No. 245-21010-15



A 10x26 grid of 'A' characters. Below the grid is a coordinate system with columns numbered 1 to 26 from right to left, and rows numbered 1 to 10 from bottom to top.



ept GmbH | Bergwerkstr. 50 | 86971 Peiting | Tel. +49 (0) 8861 / 25 01 0 | Fax +49 (0) 8861 / 55 07 | sales@ept.de | www.ept.de

Product Data Sheet

hm2.0 Male, type E,
Part No. 245-21010-15



Technical Specifications

Basics

Specification	IEC 61076-4-101
Performance Level	2
No. of Contacts	200
Termination Technology	press-fit technology
Termination Length	3.7 mm
Operating Temperature Range	-55°C to +125°C

Material

Insulator Material	glass-fiber reinforced PBT, UL 94 V-0
CTI value <i>IEC 60112</i>	200
Contact Material	Bronze

Mechanical

Pitch	2.0 mm
Mating Force per Pin	Contact: max. 0.75 N, shielding: max. 1 N
Separating Force per Pin	Contact: min. 0.15 N, shielding: min. 0.15 N
Durability	> 250 mating cycles

Electrical

Operational Current	1.5 A at +20°C, 1.0 A at +70°C
Test Voltage	750 V r.m.s.
Contact Resistance	max. 20 mΩ
Clearance and Creepage	≥ 0.8 mm
Insulation Resistance	at least 10 ⁴ MΩ
Data Transfer Rate	3.125 Gbit/s

Approval / Compliance

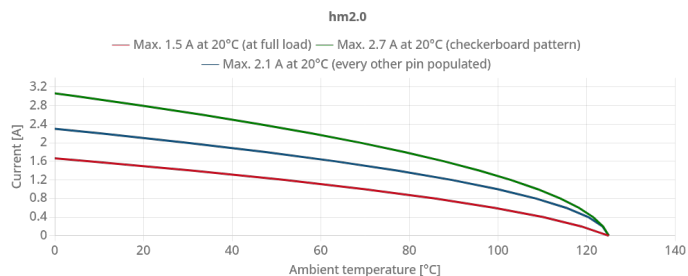
UL file	E130314
Environment	RoHS compliant

Product Data Sheet

hm2.0 Male, type E,
Part No. 245-21010-15



Derating Diagram



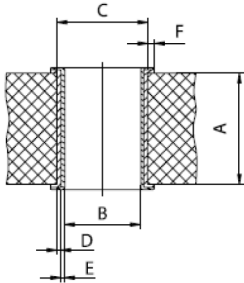
Product Data Sheet

hm2.0 Male, type E,
Part No. 245-21010-15



Hole Specifications

Plated through-hole according to IEC 60352-5



Material	chem. Sn Schicht
Nominal Hole	Ø 0.6 mm
A PCB Thickness	min. 2.2 mm
B Plated Hole	Ø 0.60 ±0.05 mm
C Drill Hole	0.70 ±0.02 mm
D Cu Plating	min. 25 µm
E Surface	max. 1.5 µm; chem. Sn Leiterplatten
F Annular Ring	min. 0.1 mm

Material	Ni, Au Leiterplatten
Nominal Hole	Ø 0.6 mm
A PCB Thickness	min. 2.2 mm
B Plated Hole	Ø 0.60 ±0.05 mm
C Drill Hole	0.70 ±0.02 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au Schicht, 0.05 - 0.2 µm Au über 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

Material	rein Cu Leiterplatten
Nominal Hole	Ø 0.6 mm
A PCB Thickness	min. 2.2 mm
B Plated Hole	Ø 0.60 ±0.05 mm
C Drill Hole	0.70 ±0.02 mm
D Cu Plating	min. 25 µm
E Surface	OSP*, z.B. GLICOAT-SMD (F2) mit 0.12 - 0.15 µm
F Annular Ring	min. 0.1 mm

Material	HAL Sn Leiterplatten
Nominal Hole	Ø 0.6 mm
A PCB Thickness	min. 2.2 mm
B Plated Hole	Ø 0.60 ±0.05 mm
C Drill Hole	0.70 ±0.02 mm
D Cu Plating	min. 25 µm
E Surface	HAL Sn, 5 - 15 µm
F Annular Ring	min. 0.1 mm

Product Data Sheet

hm2.0 Male, type E,
Part No. 245-21010-15



Modifications

Available on request

- custom loading
- Other contact plating

Drawings

Component data in 2D and 3D format you can download here:

[» PDF](#)

[» 3D IGES](#)

[» 3D STEP](#)

[» 3D PDF](#)